

prior to constructing the contact tip structure, providing a texture in an area of the sacrificial substrate, wherein the contact tip structure is formed on the area of the sacrificial substrate which is formed with the texture;

attaching an electrical interconnection element to the contact tip structure to form a first structure having the electrical interconnection element and the contact tip structure; and

removing the contact tip structure from the sacrificial substrate wherein the first structure is compliant after said removing of the contact tip structure.

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~~31~~<sup>9</sup>. (Added) The method, according to claim 30, wherein providing a texture comprises embossing.

~~32~~<sup>1</sup>. (Added) The method, according to claim 30, wherein providing a texture comprises forming a pit.

~~33~~<sup>2</sup>. (Added) The method, according to claim 30, wherein the embossing comprises forming a raised contact surface.

~~34~~<sup>3</sup>. (Added) The method, according to claim 30, wherein the contact tip structure comprises a surface layer.

~~35~~<sup>4</sup>. (Added) The method, according to claim 34, wherein the contact tip comprises a surface material which in the finished product will form a contact layer of the contact tip structure.

~~36~~<sup>5</sup>. (Added) The method, according to claim 35, wherein the surface material comprises a material suitable for making contact with an electronic component.

~~37~~<sup>6</sup>. (Added) The method, according to claim 35, wherein the surface material comprises a material selected from the group consisting of Au, Cr, Co, Ni, Pd and Pt.

<sup>7</sup>  
~~38.~~ (Added) The method, according to claim 34, wherein the contact tip comprises a protuberance.

<sup>8</sup>  
~~39.~~ (Added) The method, according to claim 38, wherein the contact tip comprises gold.

<sup>29</sup>  
~~40.~~ (Added) The method, according to claim 38, wherein the tip material comprises a material selected from the group consisting of Au, Cu, Al, Ag, Ni and combinations thereof.

A) <sup>40</sup>  
~~41.~~ (Added) The method, according to claim 34, wherein the contact tip comprises a bonding material for joining to the contact tip structure.

<sup>1</sup>  
~~42.~~ (Added) The method, according to claim 41, wherein the bonding material comprises a material suitable for bonding to an interconnection element.

<sup>2</sup>  
~~43.~~ (Added) The method, according to claim 41, wherein the bonding material comprises a material selected from the group consisting of Au, Cr, Co, Ni, Pd and Pt.

<sup>3</sup>  
~~44.~~ (Added) The method, according to claim 30, wherein the contact tip structure is formed as an enlarged end.

<sup>4</sup>  
~~45.~~ (Added) The method, according to claim 30, wherein:

the electrical interconnection element is an elongated electrical conductor with a surface layer;

the elongated electrical conductor is readily shaped and comprises a material selected from the group consisting of: gold, aluminum, copper, nickel, palladium, gold alloy and copper alloy.

<sup>5</sup>  
~~46.~~ (Added) The method, according to claim 30, wherein the electrical interconnection is elongate and provides the compliance of the first structure.

<sup>6</sup>  
~~47.~~ (Added) The method, according to claim 46, wherein the interconnection element has a compliant core element and a layer on the core element.

<sup>7</sup>  
~~48.~~ (Added) The method, according to claim 46, wherein the interconnection element has a compliant core and a layer, on the core element, comprising a material selected from the group consisting of Au, Cr, Co, Ni, Pd and Pt.

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~~49.~~ (Added) The method, according to claim 47, wherein the core element comprises gold.

<sup>49</sup>  
~~50.~~ (Added) The method, according to claim 47, wherein the core element comprises gold and the surface layer comprises a material selected from the group consisting of Au, Cr, Co, Ni, Pd and Pt.

<sup>9</sup>  
~~51.~~ (Added) The method, according to claim 47, wherein the layer comprises a material selected from the group consisting of Au, Cr, Co, Ni, Pd and Pt.

<sup>1</sup>  
~~52.~~ (Added) The method, according to claim 47, wherein the layer comprises nickel.

<sup>2</sup>  
~~53.~~ (Added) The method, according to claim 30, wherein said attaching is by a method selected from the group consisting of wire bending, solder bonding, and laser welding.

<sup>3</sup>  
~~54.~~ (Added) A method of fabricating a compliant electrical interconnection element comprising:

providing a sacrificial substrate having a texture in a region thereof;

forming an enlargement on said sacrificial substrate at said region resulting in said enlargement comprising a structure corresponding to said texture;

a compliant elongated electrical conductor being attached to said enlargement; and

removing said sacrificial substrate to form said compliant electrical interconnection element.

<sup>4</sup>  
55. (Added) A method, according to claim 54, wherein said electrical interconnection comprises a coating.

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<sup>5</sup>  
56. (Added) A method, according to claim 54, wherein said coating is selected from the group consisting of Au, Cr, Ni, Cu, Ni and Pd.

<sup>6</sup>  
57. (Added) A method, according to claim 54, wherein said electrical interconnection comprises a material selected from the group consisting of gold, gold alloy, copper, copper alloy, aluminum, nickel and palladium.

<sup>7</sup>  
58. (Added) A method, according to claim 54, wherein said texture is a pit.

<sup>8</sup>  
59. (Added) A method, according to claim 54, wherein said texture has a shape selected from the group consisting of hemispherical, rectangular and pyramidal.

<sup>59</sup>  
60. (Added) A method, according to claim 54, wherein said corresponding texture is a protuberance.

<sup>60</sup>  
61. (Added) A method, according to claim 54, wherein said texture is formed by a method selected from the group consisting of machining, stamping and embossing.

~~61~~ (Added) A method, according to claim 54, wherein said compliant elongated electrical conductor is attached to said enlargement by a method elected from the group consisting of solder bonding, wire bonding, laser welding and ultrasonic bonding.

~~62~~ (Added) A method of fabricating a compliant electrical interconnection element comprising:

providing a sacrificial substrate having a texture in a region thereof;

forming an enlargement on said sacrificial substrate at said region resulting in said enlargement comprising a structure corresponding to said texture;

a compliant elongated electrical conductor being attached to said enlargement;

removing said sacrificial substrate to form said compliant electrical interconnection element;

said electrical interconnection comprises a coating;

said coating is selected from the group consisting of Au, Cr, Ni, Cu, Ni and Pd;

said electrical interconnection comprises a material selected from the group consisting of gold, gold alloy, copper, copper alloy, aluminum, nickel and palladium;

said texture is a pit having a shape selected from the group consisting of hemispherical, rectangular and pyramidal;

said corresponding texture is a protuberance;

said texture is formed by a method selected from the group consisting of machining, stamping and embossing; and

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